



element14

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[DC-10EGWA](#)

EN

This Datasheet is presented by
the manufacturer

DE

Dieses Datenblatt wird vom
Hersteller bereitgestellt

FR

Cette fiche technique est
présentée par le fabricant

Part Number: DC-10EGWA

High Efficiency Red
Green

Features

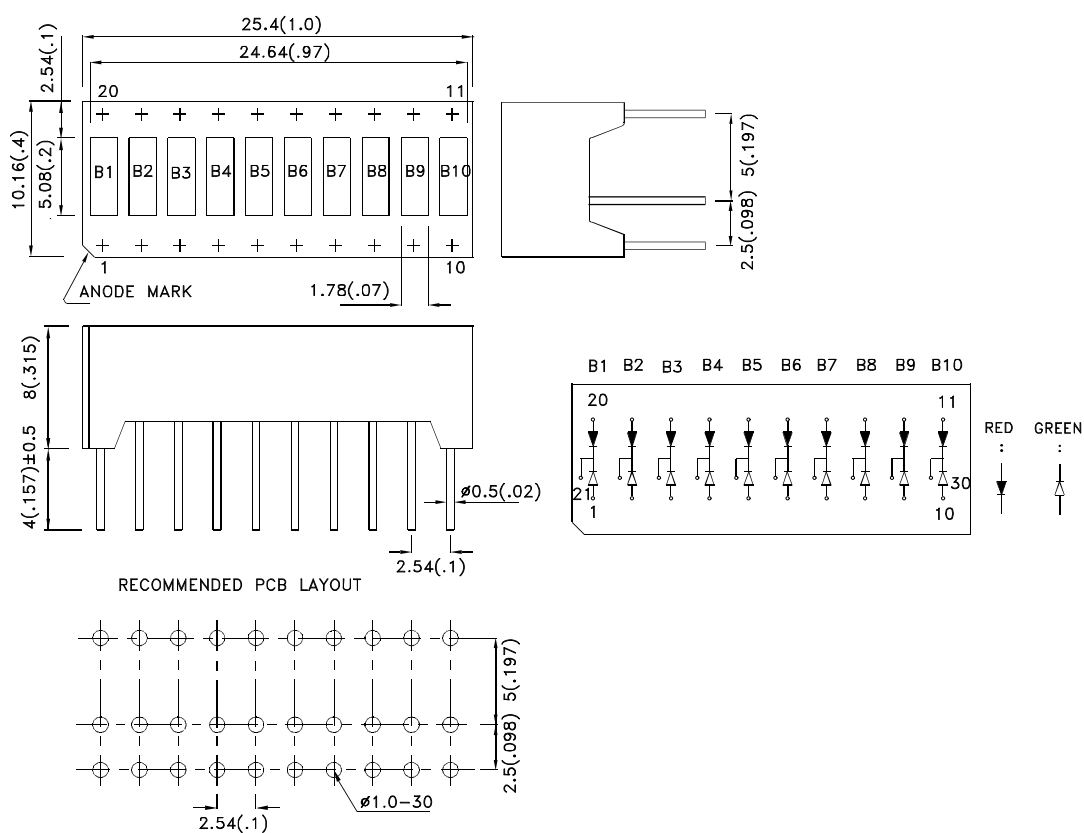
- Suitable for level indicators.
- Low current operation.
- Excellent on/off contrast.
- End stackable.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
DC-10EGWA	High Efficiency Red (GaAsP/GaP)	White Diffused	3600	9000	10 Segments Bar graph-Display
			*900	*2000	
	Green (GaP)		5600	12000	
			*1400	*2800	

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.		Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	High Efficiency Red Green	627 565	*627 *565		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	High Efficiency Red Green	625 568	*617 *568		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	High Efficiency Red Green	45 30			nm	I _F =20mA
C	Capacitance	High Efficiency Red Green	15 15			pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5		V	I _F =20mA
I _R	Reverse Current	High Efficiency Red Green			10 10	uA	V _R = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

*Wavelength value is traceable to the CIE127-2007 compliant national standards.

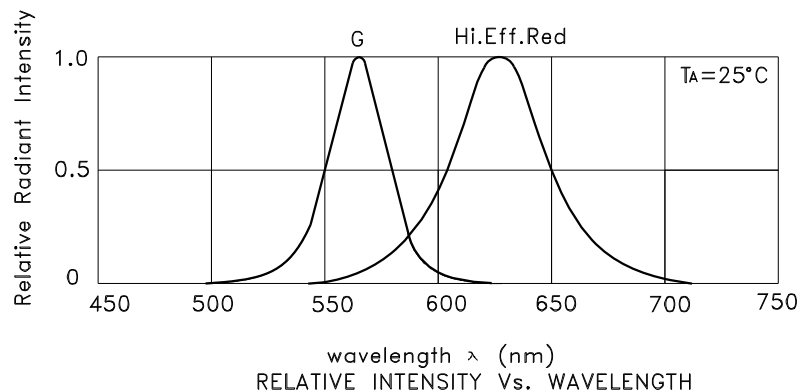
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units
Power dissipation	75	62.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	160	140	mA
Reverse Voltage	5		V
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3-5 Seconds		

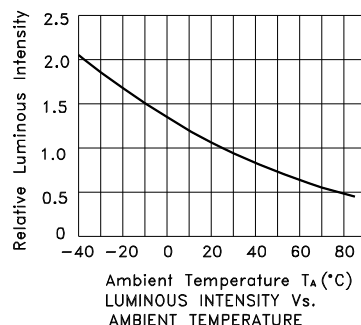
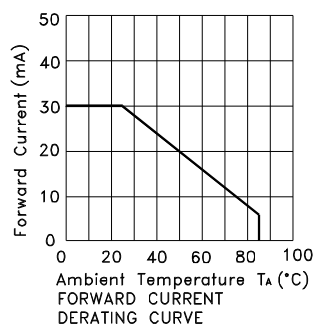
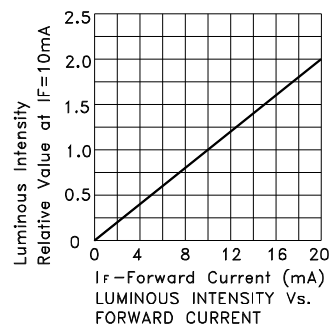
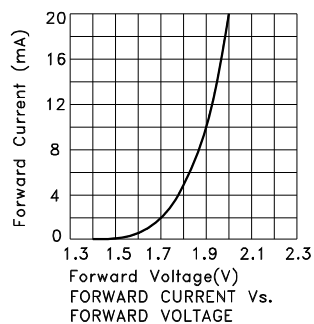
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

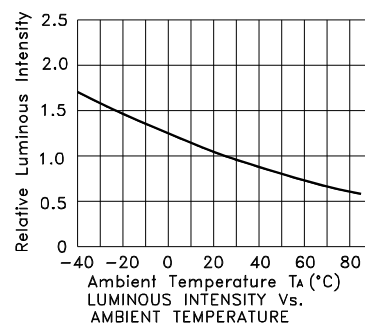
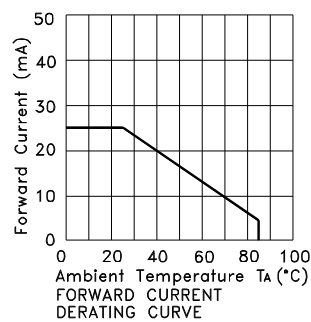
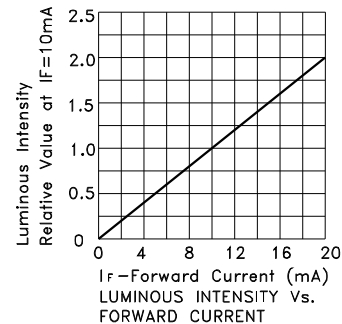
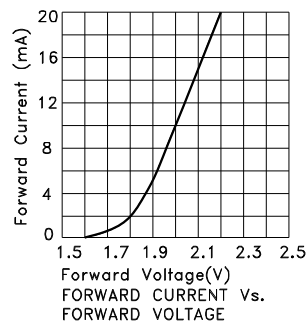
2. 2mm below package base.



DC-10EGWA High Efficiency Red

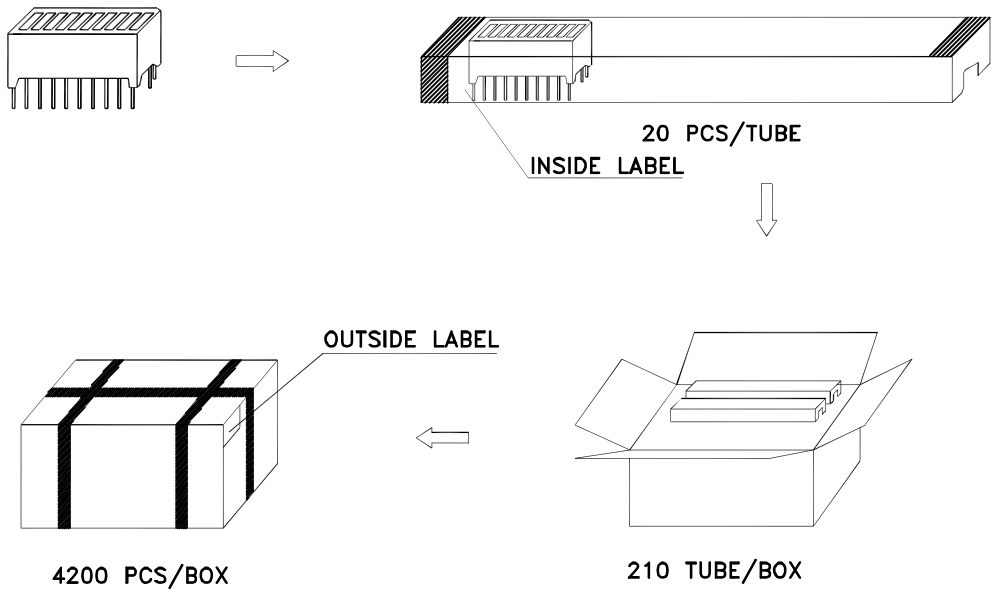


Green

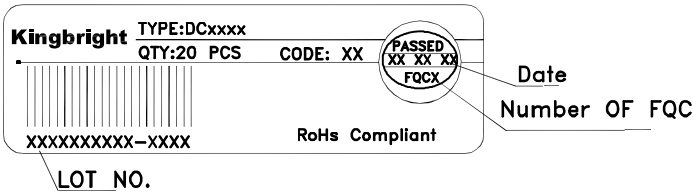


PACKING & LABEL SPECIFICATIONS

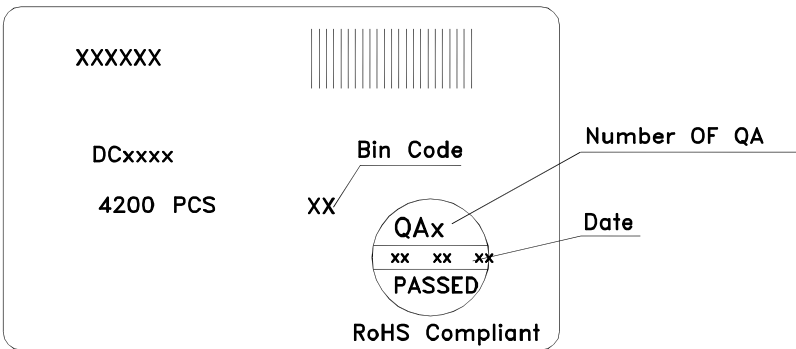
DC-10EGWA



Inside Label On IC-tube



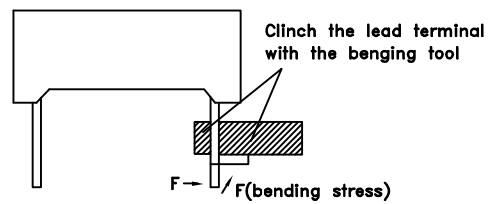
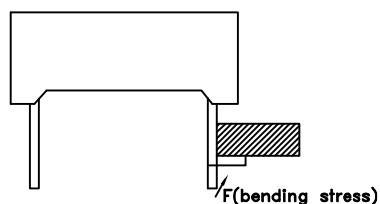
Outside Label On Box



THROUGH HOLE DISPLAY MOUNTING METHOD

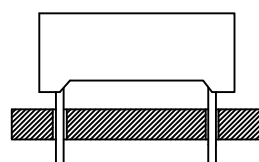
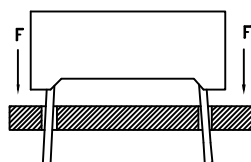
Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

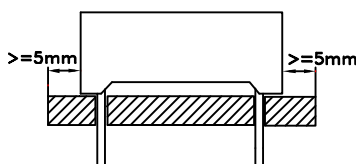
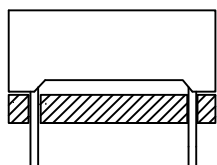


Installation

- 1.The installation process should not apply stress to the lead terminals.
- 2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

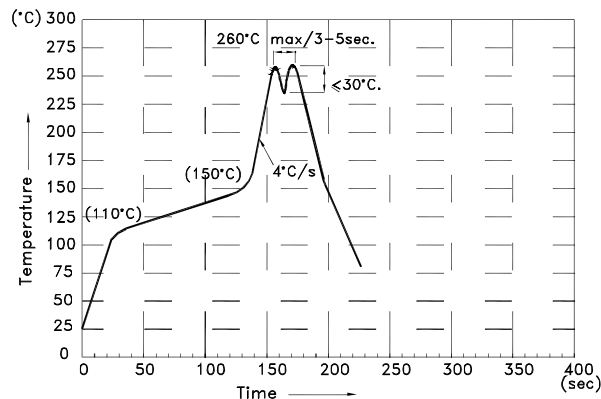


- 3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C
5. No more than once.

Soldering General Notes:

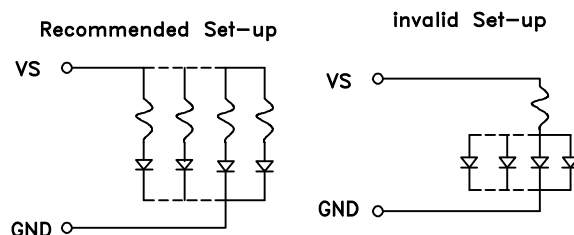
1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.





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